



600 V PowerPAK[®] 8 x 8LR + Gen 4 Superjunction MOSFETs

Top-Side Cooling Package for Under 3 kW Power Supply Solutions

KEY FEATURES

- Low profile, dimensions: 7.9 mm x 10.2 mm x 1.6 mm
- Top-side cooling
- Kelvin source connection
- Extremely low R_{thjc} , 0.25 °C/W
- Industry lowest $R_{DS(on)} \times Q_g$ FOM
- Excellent temperature cycle capability, passed 1000 cycles

Parameter	D ² PAK	PowerPAK 8 x 8LR
Height (mm)	4.45	1.6
Footprint (mm ²)	169.4	80.6
R_{thjc} (°C/W)	0.55	0.25
I_o current (A)	35	51

	$R_{DS(on)}$ (max.)	Q_g (typ.)	Q_{gd} (typ.)	Q_{gs} (typ.)
SiHR080N60E	84 mΩ	42 nC	10 nC	19 nC
SiHB080N60E	80 mΩ	42 nC	10 nC	19 nC



TOP-SIDE COOLING POWERPAK 8 x 8LR VS. BOTTOM-SIDE COOLING D²PAK

- Only 36 % of the height of D²PAK
- Saves 52.4 % of space
- 2.25 times better thermal capability
- 45 % better ID current capability
- Enables higher power rating and power density

APPLICATIONS



SOLAR / PV INVERTER



MOTION CONTROL



SERVERS / DATACENTERS



UPS



TELECOM



GAMING PC

